

Amendments to the claims:

This listing of claims will replace all prior versions and listing, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A photosensitive resin composition in the form of an aqueous emulsion ~~type~~ comprising:

(A) an emulsion of a photosensitive water-insoluble polymer, the emulsion being obtained by reacting (i) an aqueous polymer emulsion which contains a water-insoluble polymer as its main component and which contains a polymer having a hydroxyl group with (ii) an N-alkylol(meth)acrylamide;

(B) at least one a compound monomer having a at least one photoreactive ethylenically unsaturated group; and

(C) a photopolymerization initiator.

Claim 2 (original): A photosensitive resin composition according to claim 1 wherein the aqueous polymer emulsion (A) (i) contains a water-insoluble polymer and a protective colloid comprising a polymer having a hydroxyl group.

Claim 3 (original): A photosensitive resin composition according to claim 1 further comprising (E) an epoxy compound having at least two epoxy groups per molecule.

Claim 4 (currently amended): A photosensitive resin composition according to claim 1 ~~which contains (b) a compound having at least one carboxyl group per molecule and at least one photoreactive ethylenically unsaturated group per molecule as the ingredient (B)~~ wherein the component (B) comprises a monomer (b) having at least one carboxyl group and at least one photoreactive ethylenically unsaturated group in a molecule.

Claims 5-7 (canceled)

Claim 8 (currently amended): A ~~photosensitive resin composition according to any of claims 1-6 which is used as a photoresist ink for manufacturing a printed wiring board~~ produced by using the photosensitive resin composition according to any one of claims 1-4.

Claim 9 (currently amended): A ~~photosensitive resin composition~~ photoresist ink according to claim 8 which is used as a photoetching resist ink, a plating resist ink or a solder resist ink.

Claim 10 (currently amended): A method for producing a screen printing stencil comprising:

(I) a step of providing a photosensitive resin composition ~~recited in any~~ according to any one of claims 1-[6] 4;

- (II) a step of forming a film comprising the photosensitive resin composition on a screen;
- (III) a step of selectively exposing the film to form a cured film on the screen; and
- (~~VI~~ IV) a step of washing away to remove a non-exposed portion of the film.

Claim 11 (currently amended): A method for producing a screen printing stencil comprising:

- (I) a step of providing a photosensitive resin composition ~~recited in any~~ according to any one of claims 1-[6] 4;
- (II) a step of forming a film of the photosensitive resin composition on a releasable film;
- (III) a step of selectively exposing the film to form a cured film;
- (~~VI~~ IV) a step of washing away to remove a non-exposed portion of the film; and
- (V) a step of transferring the resulting cured film onto a screen.

Claim 12 (currently amended): A screen printing stencil produced by using the photosensitive resin composition ~~recited in any~~ according to any one of claims 1-[6] 4.

Claim 13 (original): A screen printing stencil according to claim 12 which is a thick screen printing stencil.

Claim 14 (currently amended): A ~~method for producing a printed wiring board wherein~~

produced by using the photosensitive resin composition ~~recited in any~~ according to any one of claims 1-[6] 4 ~~is used~~.

Claim 15 (original): A method for producing a printed wiring board according to claim 14 comprising:

- (I) a step of providing a substrate having a metallic layer formed on its surface;
- (II) a step of applying the photosensitive resin composition to the surface of the substrate and then drying it;
- (III) a step of selectively exposing a predetermined portion of the photosensitive resin composition which is applied to the substrate to form a cured film;
- (IV) a step of washing away to remove the non-exposed portion of the photosensitive resin composition;
- (V) a step of immersing the substrate in an etching solution to subject a part of the metallic layer to be etched; and
- (VI) a step of removing the cured film.

Claim 16 (original): A method for producing a printed wiring board according to claim 14 comprising:

- (I) a step of providing a substrate with a conductive circuit formed on its surface;
- (II) a step of applying the photosensitive resin composition to the surface of the substrate

and then drying it;

(III) a step of selectively exposing a predetermined portion of the photosensitive resin composition which is applied to the substrate to form a cured film; and

(IV) a step of washing away to remove the non-exposed portion of the photosensitive resin composition.

Claim 17 (original): A method for producing a printed wiring board according to claim 16 further comprising a step of heating the cured film to obtain a permanent protective coating.

Claim 18 (currently amended): A printed wiring board with a cured film on its surface, the cured film being made from the photosensitive resin composition according to any one of claims 1-[6] 4.

Claim 19 (original): A printed wiring board according to claim 18 wherein the cured film is a permanent protective coating.

Claim 20 (new): A photosensitive resin composition of an aqueous emulsion type comprising:

(A) an emulsion of a photosensitive water-insoluble polymer, the emulsion being obtained by reacting (i) an aqueous polymer emulsion which contains a water-insoluble polymer as its main

N-alkylol(meth)acrylamide;

(B) at least one monomer having at least one photoreactive ethylenically unsaturated group;

(C) a photopolymerization initiator; and

(D) a binder resin having a carboxyl group.

Claim 21 (new): A photosensitive resin composition according to claim 20 wherein the binder resin having a carboxyl group as the ingredient (D) has a photopolymerizable unsaturated group.

Claim 22 (new): A photosensitive resin composition according to claim 20, wherein the aqueous polymer emulsion (A) (i) contains a water-insoluble polymer and a protective colloid comprising a polymer having a hydroxyl group.

Claim 23 (new): A photosensitive resin composition according to claim 20; further comprising (E) an epoxy compound having at least two epoxy groups per molecule.